



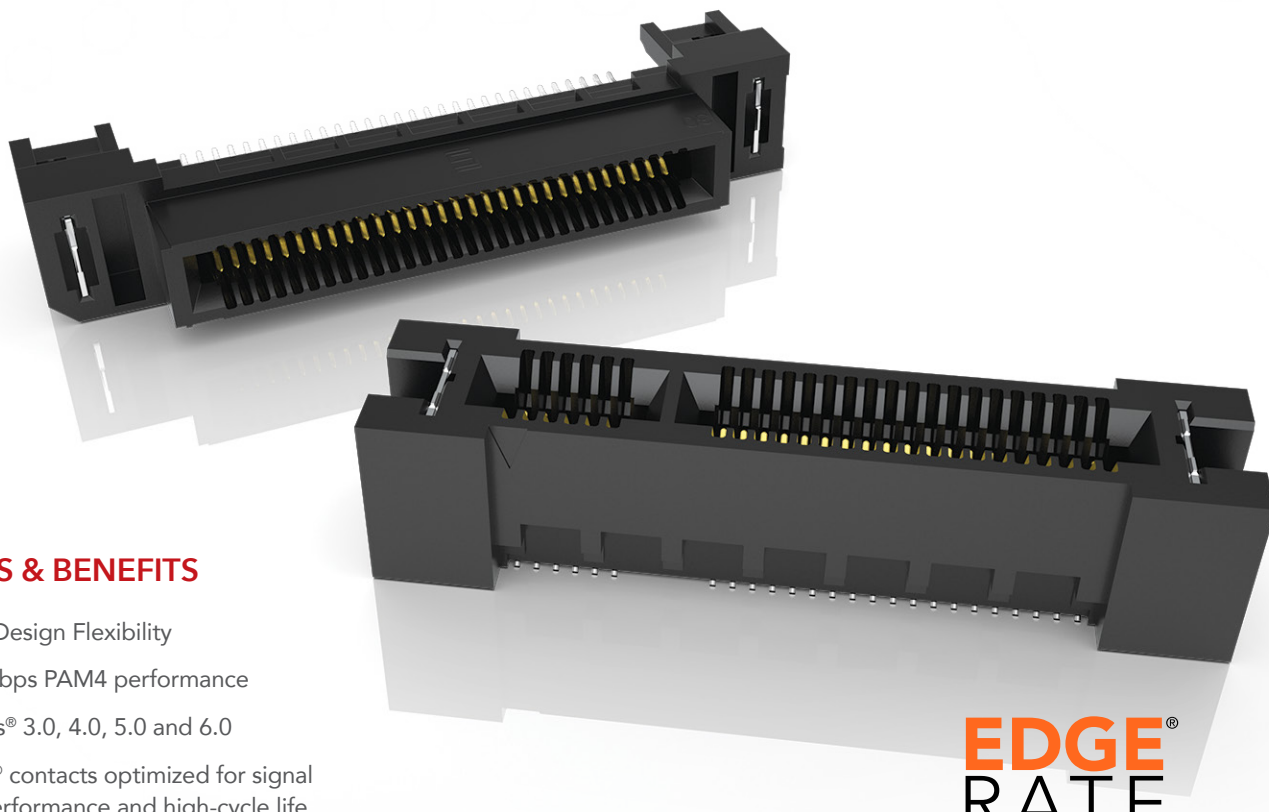
**THE DATASHEET OF  
HSEC8-160-01-S-RA-TR**



# GENERATE<sup>®</sup>

## HIGH-SPEED EDGE CARD SYSTEMS

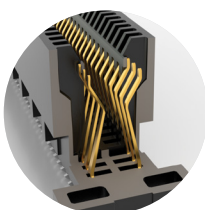
0.60 mm, 0.80 mm and 1.00 mm PITCH



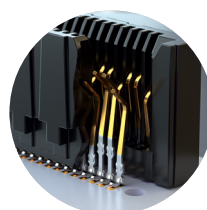
### FEATURES & BENEFITS

- Maximum Design Flexibility
- Up to 64 Gbps PAM4 performance
- PCI Express<sup>®</sup> 3.0, 4.0, 5.0 and 6.0
- Edge Rate<sup>®</sup> contacts optimized for signal integrity performance and high-cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available

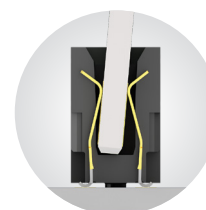
**EDGE  
RATE<sup>®</sup>**  
CONTACT



Rugged tucked beam technology (HTEC8)



Differential pair for increased speed (HSEC8-DP)



Custom designs allow for misalignment in the X-Y axes (HSEC1)

### KEY SPECIFICATIONS

SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	1.9 A (2 pins)	240 VAC	Yes
HTEC8	0.80 mm	20-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC	Yes
HSEC8	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC	Yes

**(0.80 mm) .0315" PITCH • RIGHT-ANGLE & EDGE MOUNT SOCKET**

<b>HSEC8</b>	<b>1</b>	<b>POSITIONS PER ROW</b>	<b>CARD THICKNESS</b>	<b>PLATING OPTION</b>	<b>RA</b>	<b>OTHER OPTIONS</b>	<b>"X"R</b>
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09, 10, 13,  
20, 25, 30,  
40, 49, 50, 60

**-01**  
= (1.60 mm) .062"  
thick card

**-L**  
= 10 μ" (0.25 μm)  
Gold on contact area,  
Matte Tin on tail

**-S**  
= 30 μ" (0.76 μm)  
Gold on contact area,  
Matte Tin on tail

**-BL**  
= Board Locks  
(09, 13, 25, 40,  
49, 50, 60 only)

**-L2**  
= ECDP Latching  
(09, 13, 25, 49 only)

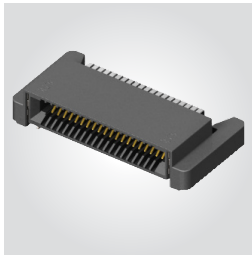
Leave blank for  
Tray Packaging

**-TR**  
= Tape & Reel

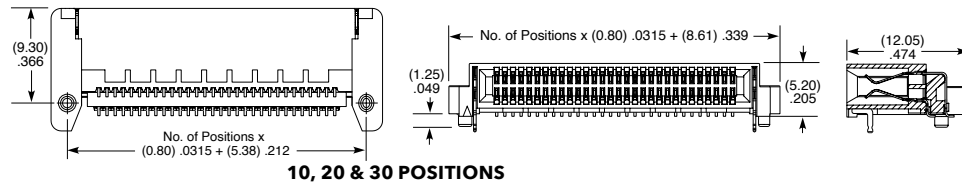
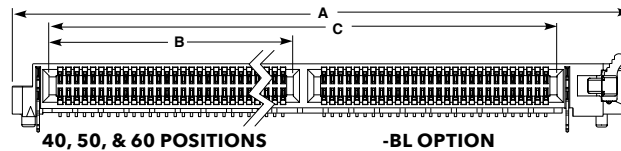
**-FR**  
= Full Reel  
Tape & Reel Packaging  
(must order max.  
quantity per reel;  
contact Samtec for  
quantity breaks)

**HSEC8-RA**

**Card Mates:**  
(1.60 mm) .062"  
thick card,  
**HSC8**  
**Cable Mates:**  
**ECDP**



POSITIONS PER ROW	A	B	C
40	(43.80) 1.724	(18.90) .744	(36.60) 1.441
50	(51.80) 2.039	(22.90) .902	(44.60) 1.756
60	(59.80) 2.354	(26.90) 1.059	(52.60) 2.071
40-BL	(51.30) 2.020	(18.90) .744	(36.60) 1.441
50-BL	(59.30) 2.335	(22.90) .902	(44.60) 1.756
60-BL	(67.30) 2.650	(26.90) 1.059	(52.60) 2.071



View complete specifications at: [samtec.com?HSEC8-RA](http://samtec.com?HSEC8-RA)

<b>HSEC8</b>	<b>1</b>	<b>POSITIONS PER ROW</b>	<b>01</b>	<b>PLATING OPTION</b>	<b>D</b>	<b>EM2</b>
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10, 20, 30, 40, 50, 60

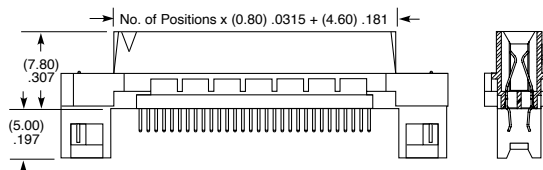
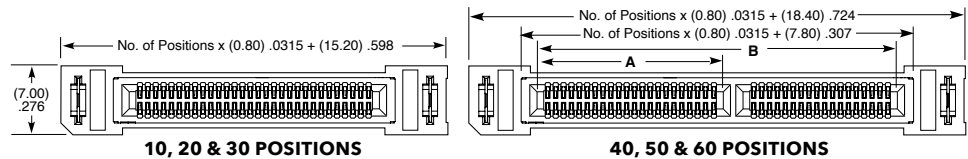
**-L**  
= 10 μ" (0.25 μm)  
Gold on contact area,  
Matte Tin on tail

**-S**  
= 30 μ" (0.76 μm)  
Gold on contact area,  
Matte Tin on tail

**-EM2**  
= (1.60 mm) .062"  
thick PCB

**HSEC8-EM**

**Card Mates:**  
(1.60 mm) .062"  
thick card,  
**HSC8**  
**Cable Mates:**  
**ECDP**





POSITIONS PER ROW	A	B
40	(18.90) .744	(36.60) 1.441
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071

View complete specifications at: [samtec.com?HSEC8-EM](http://samtec.com?HSEC8-EM)

**Note:**  
Some sizes, styles and  
options are non-standard,  
non-returnable.

## Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

-  [View HSEC8-160-01-S-RA-TR on WIN SOURCE](#)
-  [Samtec Inc. Information](#)

## Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management